



## Materials Declaration Form

<b>IPC</b>	<b>1752</b>	<b>Version</b>	<b>2</b>
<b>Form Type *</b>	<b>Distribute</b>		
<b>Sectionals *</b>	<b>Material Info</b> <b>Manufacturing Info</b>	<b>Subsectionals *</b>	<b>A-D</b>

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>2020-10-15</b>
<b>Company Unique ID</b>	<b>NL 008751171B01</b>		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	<b>giovanni giacopello</b>	<b>Representative Title</b>	<b>ADG MD CHAMPION</b>
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	<b>true</b>	<b>Legal Declaration *</b>	<b>Standard</b>
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STGB30M65DF2	XDD2*KLF5R52	A	3068	2020-10-15
	Amount	UoM	Unit type	ST ECOPACK Grade
	1380	mg	Each	ECOPACK 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	245	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	DM00264152	



Package Designator	Size	Nbr of instances	Shape	
SIP	10.20,9.15,4.50	3	gull wing	
Comment	D2PAK			

QueryList : RoHS Directive 2011/65/EU-July 2011 Annex II amended by Delegated Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2020/363_ March 2020	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 3rd January 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.20	leadframe	147
Lead	8.08	soft solder	5857

QueryList : REACH-25th June 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	8.08	Soft solder	5857
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	8.082	Soft solder	954981

Responsible metals sourcing	
Query	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Gold, Tin, Tungsten,
This product is in the scope of the responsible metals sourcing, its compliance is covered by our company processes .	

Material Composition Declaration :						Mfr Item Name	XDD2*KLF5R52					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	7.316	mg	supplier	die	Silicon(Si)	7440-21-3		6.914	mg	945053	5009
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.165	mg	22553	120
				supplier	metallisation	Chromium(Cr)	7440-47-3		0.011	mg	1504	8
				supplier	metallisation	Gold(Au)	7440-57-5		0.007	mg	957	5
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.098	mg	13395	71
				supplier	metallisation	Silver(Ag)	7440-22-4		0.026	mg	3554	19
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.008	mg	1093	6
				supplier	metallisation	Tungsten(W)	7440-33-7		0.007	mg	957	5
				supplier	metallisation	Vanadium(V)	7440-62-2		0.005	mg	683	4
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.031	mg	4237	22
Leadframe	M-004 Copper and its alloys	778.660	mg	supplier	passivation	Silicon oxide	7631-86-9		0.044	mg	6014	32
				supplier	alloy & coating	Copper(Cu)	7440-50-8		777.532	mg	998551	563429
				supplier	alloy & coating	Nickel(Ni)	7440-02-0		0.105	mg	135	76
				supplier	alloy & coating	Iron(Fe)	7439-89-6		0.358	mg	460	259
				supplier	alloy & coating	Iron Phosphide(FeP)	26508-33-8		0.654	mg	840	474
Soft solder	Solder	8.463	mg	SVHC	alloy & coating	Phosphorus metal	7723-14-0		0.011	mg	14	8
				supplier	solder	Lead(Pb)	7439-92-1	7a-Lead in high melting temper	8.082	mg	954981	5857
				supplier	solder	Silver(Ag)	7440-22-4		0.212	mg	25050	154
				supplier	solder	Tin(Sn)	7440-31-5		0.169	mg	19969	122
Bonding wires	M-003 Aluminum and its alloys	4.340	mg	supplier	wire	Aluminium (Al)	7429-90-5		4.340	mg	1000000	3145
Bonding wires 2	M-003 Aluminum and its alloys	0.132	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.131	mg	992424	95
				supplier	wire	Magnesium (Mg)	7439-95-4		0.001	mg	7576	1
Encapsulation	M-011 Other inorganic materials	578.600	mg	supplier	mold compound	Silica vitreous	60676-86-0		506.275	mg	875000	366866
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		23.144	mg	40000	16771
				supplier	mold compound	Epoxy type resin	proprietary		17.358	mg	30000	12578
				supplier	mold compound	Phenol type resin	proprietary		28.930	mg	50000	20964
				supplier	mold compound	Carbon black	1333-86-4		2.893	mg	5000	2096
connections coating	Solder	2.489	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		2.489	mg	1000000	1804